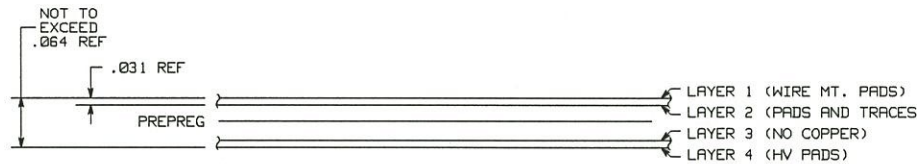
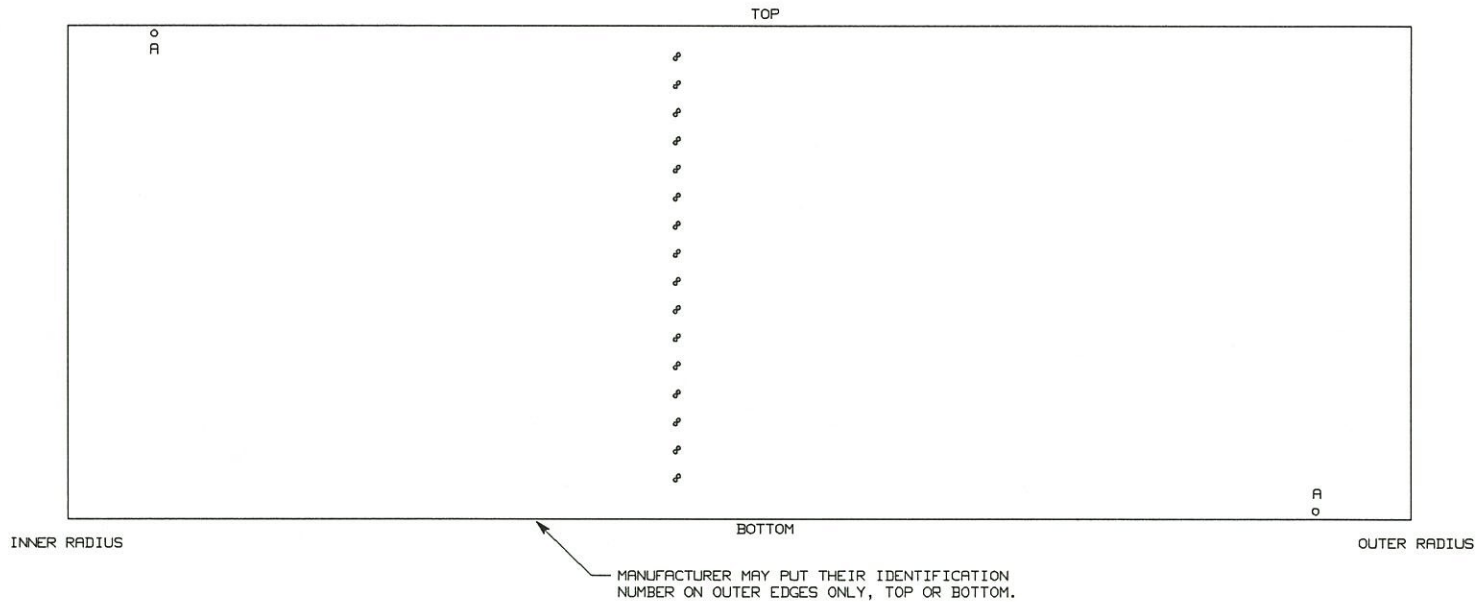


REV.	CHANGES	DRAWN	DATE	CHKD.	DATE
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LAYER FOUR VIEW
SCALE: NONE



USE .015 DIA HOLE (5,440 HOLES)
THESE HOLES ONLY GO THROUGH
LAYERS 1 AND 2 (BLIND VIAS).
SEE DRAWING 24A4503 E-2.

USE .028 DIA HOLE (32 HOLES).
DRILL THESE HOLES AFTER ASSEMBLY
OF ALL LAYERS, SEE THIS DRAWING.

NOTES:

- BOARD MATERIAL: .031 THICK G10 PER MIL-P-55617 FL-GEN 031C-1/1-A1A (1 OZ. COPPER EACH SIDE). THIS IS A MULTILAYER BOARD (4 LAYERS). TOTAL THICKNESS NOT TO EXCEED .064.
- PLEASE NOTE THAT THERE IS NO COPPER ON LAYER 3.
- THIS BOARD TO BE THROUGH HOLE PLATED.
- SPECIFIED HOLE DIA. SIZES ARE FOR FINISHED HOLES AFTER PLATING.
- BOARD SIZE IS 10.500 +/- .010 X 28.100 +/- .005. DIMENSIONS ARE IN INCHES. BOARD OUTLINE DRAWING IS 24A4503 M-2 (a000896m2).
- SOLDERMASK IS NOT USED ON THIS BOARD.
- REFERENCE DRAWINGS:

24A4502 M-1	a000896m1	BOARD OUTLINE - SINGLE BOARD
24A4503 M-2	a000896m2	BOARD OUTLINE - PANEL OF 16
24A4502 E-1	a000896e1	HOLE SCHEDULE - SINGLE BOARD
24A4503 E-2	a000896e2	HOLE SCHEDULE - PANEL OF 16, BLIND VIAS

HOLE SCHEDULE		
CODE	HOLE DIA.	COUNT
NONE	.028	32
A	.125	2

I:		TITLE STAR TPC	
II:		INNER SECTOR ELECTRONICS	
III:		GATED GRID WIRE MOUNT BOARD - PANEL OF 16	
SHOW ON:		HOLE SCHEDULE - 24A4501 U-2 (A000896U2)	
ACCOUNT NUMBER	8052-24	DRAWN	DATE
SERIAL NUMBER		STIRAKKINEN	4/08/84
DATE ISSUED		CHECKED	DATE
DATE RECD.		APPROVED	DATE
DEL. TO		ENGINEER	JIM HUNTER
		FILE NO.	a000896e3
		SIZE	3
		DRAWING NO.	24A4503 E-3
		REV.	
		SCALE	NONE
			E14
			SHEET 3 of 3